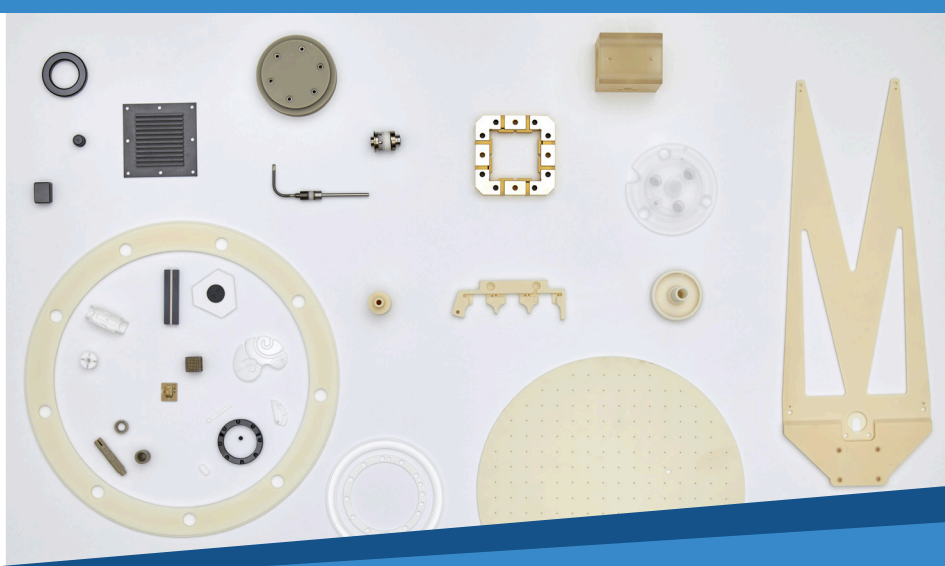


CERAMIC 3D INTERCONNECT DEVICES



TECHNOLOGY

- › High-precision 2D and 3D ceramic components manufacturing
- › Ceramic materials : alumina, aluminium nitride
- › Circuit materials : thin-film PVD Cr/Au, NiCr/Au, Cr/Ni/Au, Ti/Pt/Au, TiW/Au, Cu, Ag...
- › High-accuracy laser ablation of electrical patterns and solder pads : track width 50 μm (0.002"), insulation pad 50 μm (0.002") general tolerances < 20 μm (0.0008")
- › Full wrap-over technology
- › Product size < 1 cm³ up to a few cm³
- › Layers suitable for standard bonding or brazing processes



PRODUCTS - APPLICATIONS

Our typical products

- › Chip carriers, substrates, 2.5D and 3D interconnected circuits

Applications

- › MEMS, LED's
- › Optical transponders, infra-red detectors ..
- › Sensors, probes, antenna modules....

Industries

- › Optoelectronics, microelectronics, analytical equipment, aerospace, medical, off-shore, energy...



BENEFITS

- › High-performance ceramic materials
- › Dimension stability (heat, temperature variations)
- › Resistance to vibrations
- › Electrical insulation
- › Heat dissipation
- › No outgasing in vacuum
- › Chemical inertness
- › Mechanical and electrical functions on the same carrier

